

## 650V N-Channel MOSFET

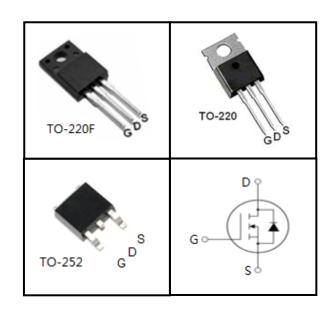
#### **FEATURES**

- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

#### **APPLICATIONS**

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)

Device Marking and Package Information				
Device	Package	Marking		
CS8N65F	TO-220F	CS8N65F		
CS8N65P	TO-220	CS8N65P		
CS8N65D	TO-252	CS8N65D		
CS8N65F-B	TO-220F-B	CS8N65F-B		



<b>Absolute Maximum Ratings</b> T <sub>C</sub> = 25°C, unless otherwise noted						
Dorometer	Symbol	Value			l lmit	
Parameter		TO-220F	TO-220	TO-252	Unit	
Drain-Source Voltage (V <sub>GS</sub> = 0V)	V <sub>DSS</sub>	650		V		
Continuous Drain Current	I <sub>D</sub>	8			А	
Pulsed Drain Current (note1)	I <sub>DM</sub>	32			А	
Gate-Source Voltage	V <sub>GSS</sub>	±30		V		
Single Pulse Avalanche Energy (note2)	E <sub>AS</sub>	245			mJ	
Avalanche Current (note1)	I <sub>AS</sub>	7		А		
Repetitive Avalanche Energy (note1)	E <sub>AR</sub>	147		mJ		
Power Dissipation (T <sub>C</sub> = 25°C)	P <sub>D</sub>	64 107		W		
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55~+150		°C		

Thermal Resistance					
Parameter	Symbol	Value			11
		TO-220F	TO-220	TO-252	Unit
Thermal Resistance, Junction-to-Case	R <sub>thJC</sub>	1.95	1.17		°C/W
Thermal Resistance, Junction-to-Ambient	R <sub>thJA</sub>	62.5	60		30/00

<b>Specifications</b> $T_J = 25^{\circ}C$ , unless otherwise noted							
Parameter	Symbol	Total Complisions	Value			1121	
		Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	650			V	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 650V, V_{GS} = 0V, T_{J} = 25^{\circ}C$			1	μA	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{GS} = \pm 30V$			±100	nA	
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	3.0		4.0	V	
Drain-Source On-Resistance (Note3)	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 4A		0.95	1.15	Ω	
Dynamic							
Input Capacitance	C <sub>iss</sub>	$V_{GS} = 0V,$ $V_{DS} = 25V,$ $f = 1.0MHz$		1110		pF	
Output Capacitance	$C_{oss}$			106			
Reverse Transfer Capacitance	$C_{rss}$			13			
Total Gate Charge	$Q_g$	$V_{DD} = 520V, I_D = 8A,$ $V_{GS} = 10V$		37			
Gate-Source Charge	$Q_{gs}$			5		nC	
Gate-Drain Charge	$Q_{gd}$			24			
Turn-on Delay Time	t <sub>d(on)</sub>			39			
Turn-on Rise Time	t <sub>r</sub>	$V_{DD} = 325V, I_{D} = 8A,$		10		ns	
Turn-off Delay Time	t <sub>d(off)</sub>	$R_G = 25 \Omega$		152			
Turn-off Fall Time	t <sub>f</sub>			42			
Drain-Source Body Diode Character	istics						
Continuous Body Diode Current	I <sub>S</sub>	<b>T</b>			8	^	
Pulsed Diode Forward Current	I <sub>SM</sub>	T <sub>C</sub> = 25 °C			32	A	
Body Diode Voltage	V <sub>SD</sub>	$T_J = 25^{\circ}\text{C}, I_{SD} = 4\text{A}, V_{GS} = 0\text{V}$			1.4	V	
Reverse Recovery Time	t <sub>rr</sub>	$V_{GS} = 0V, I_{S} = 8A,$		601		ns	
Reverse Recovery Charge	Q <sub>rr</sub>	di <sub>F</sub> /dt =100A /µs		2.3		μC	

#### Notes

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. L = 10mH,  $V_{DD}$  = 50V,  $R_G$  = 25  $\Omega$ , Starting  $T_J$  = 25  $^{\circ}C$
- 3. Pulse Test: Pulse width ≤ 325µs, Duty Cycle ≤ 1%



### **Typical Characteristics** $T_J = 25^{\circ}\text{C}$ , unless otherwise noted

Figure 1. Output Characteristics ( $T_J = 25^{\circ}C$ )

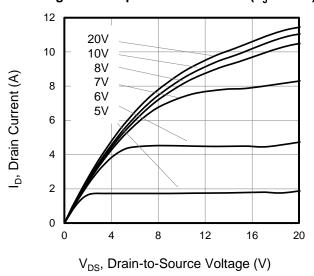


Figure 3. Drain Current vs. Temperature

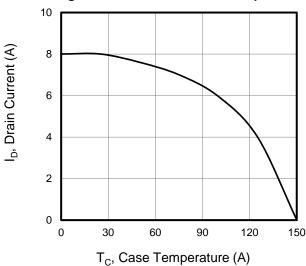


Figure 5. Transfer Characteristics

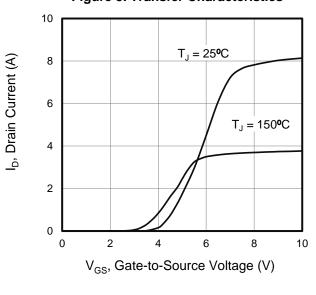
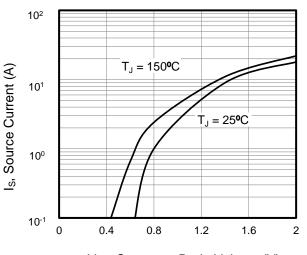
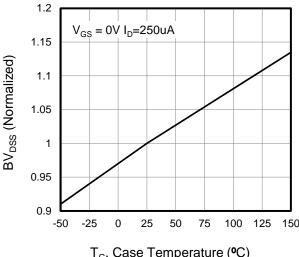


Figure 2. Body Diode Forward Voltage



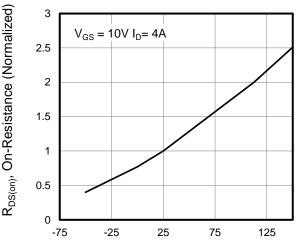
V<sub>SD</sub>, Source-to-Drain Voltage (V)

Figure 4. BV<sub>DSS</sub> Variation vs. Temperature



T<sub>C</sub>, Case Temperature (°C)

Figure 6. On-Resistance vs. Temperature



T<sub>J</sub>, Junction Temperature (°C)



### **Typical Characteristics** $T_J = 25^{\circ}\text{C}$ , unless otherwise noted

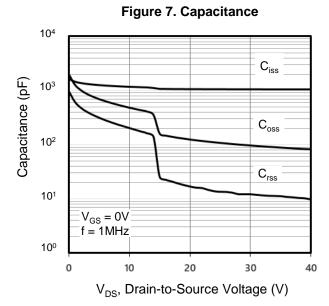


Figure 9. Transient Thermal Impedance

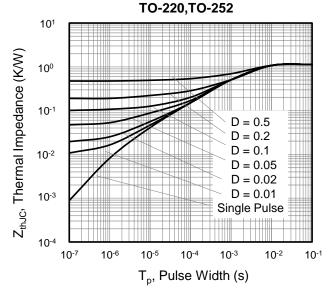


Figure 8. Gate Charge

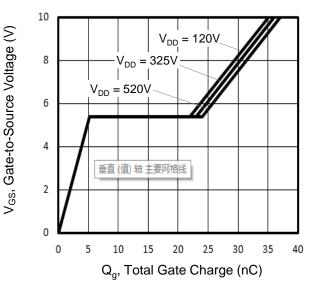


Figure 10. Transient Thermal Impedance

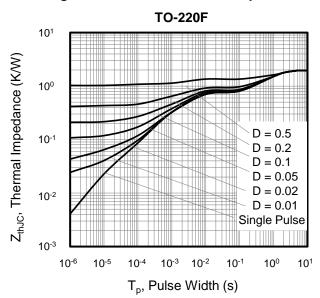




Figure A: Gate Charge Test Circuit and Waveform

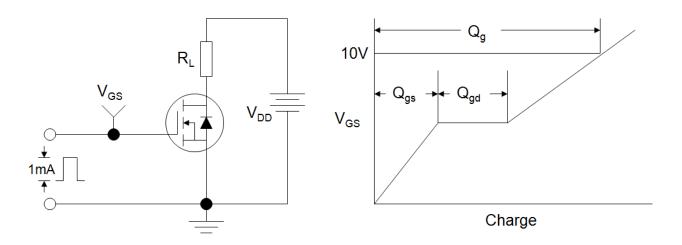


Figure B: Resistive Switching Test Circuit and Waveform

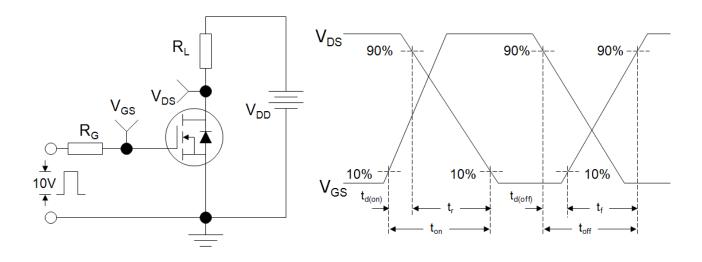
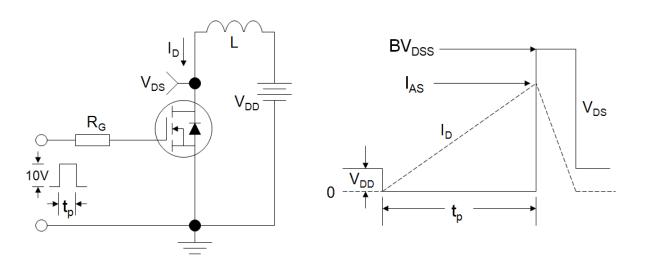
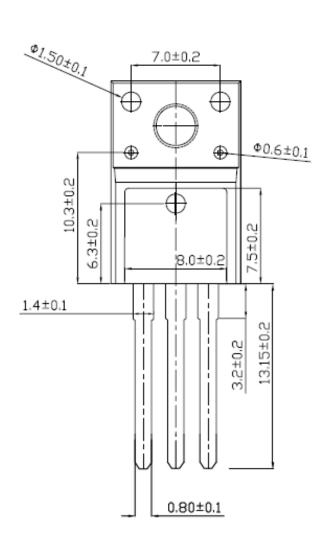


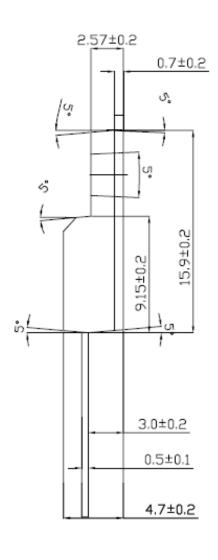
Figure C: Unclamped Inductive Switching Test Circuit and Waveform





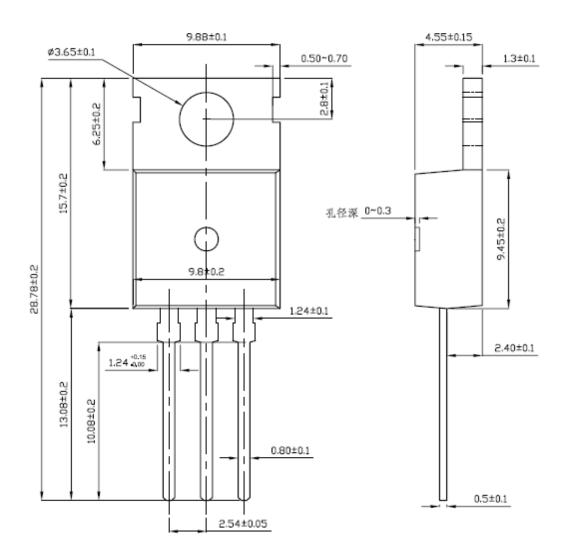
## **TO-220F**





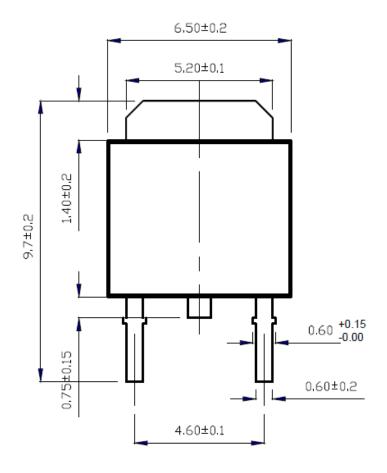


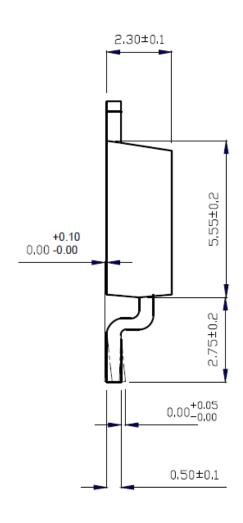
# **TO-220**





**TO-252** 







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